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Docket No. ЙENT TRANSMITTAL LETTER 0171-1015P Filing Date Application No. Examiner Art Unit 10/659,266-Conf. #3533 September 11, 2003 R. E. Sellers 1712 Applicant(s): Kazuaki SUMITA et al. Invention: LIQUID EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE MS Amendment **Commissioner for Patents** P.O. Box 1450 Alexandria, VA 22313-1450 Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below. **CLAIMS AS AMENDED** Claims Highest Remaining Number Number After Previously **Extra Claims** Amendment Paid Present Rate 20 **Total Claims** 6 Х Independent 3 Х Claims Multiple Dependent Claims (check if applicable) Other fee (please specify): TOTAL ADDITIONAL FEE FOR THIS AMENDMENT: 0.00 Small Entity x Large Entity x No additional fee is required for this amendment. Please charge Deposit Account No. in the amount of \$ A duplicate copy of this sheet is enclosed. A check in the amount of \$ is enclosed. Payment by credit card. Form PTO-2038 is attached. | x | The Director is hereby authorized to charge and credit Deposit Account No. 02-2448 as described below. A duplicate copy of this sheet is enclosed. x Credit any overpayment. Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17. Dated: February 22, 2006 Gerald M. Murphy, ďr. Attorney Reg. No.: 28,977 BIRCH, STEWART, KOLASCH & BIRCH, LLP 8110 Gatehouse Road Suite 100 East P.O. Box 747 Falls Church, Virginia 22040-0747 (703) 205-8000



Docket No.: 0171-1015P

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Kazuaki SUMITA, et al.

Application No.: 10/659,266 Confirmation No.: 3533

Filed: September 11, 2003 Art Unit: 1712

For: LIQUID EPOXY RESIN COMPOSITION AND

SEMICONDUCTOR DEVICE

Examiner: R. E. SELLERS

AMENDMENT UNDER 37 CFR 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated December 23, 2005, please amend the above-identified U.S. patent application as follows:

This response includes:

Amendment to the specification;

Amended Claim Set; and

Remarks.